

REV	MODIFICATION	DATE	DRAW
A1	Release To ECN20130303	2013.03.12	Seven
A2	Release To ECN20150201	2015.02.02	Michelle
A3	Release To ECN20160203	20160219	Michelle

**RoHS Compliant**

- Specification
- 1.Current Rating:2.5A AC/DC
  - 2.Voltage Rating:250V AC/DC
  - 3.Contact Resistance:20mΩ Max.
  - 4.Insulation Resistance:1000MΩ Min. At DC 500V
  - 5.Dielectric Withstanding Voltage:AC600V/Minute
  - 6.Operating Temperature:-25°C~+85°C

Material:

- 1.Housing:Thermoplastic UL94V-0
- 2.Contact Pin:Copper Alloy SQ. Pin 0.64mm

Finish:

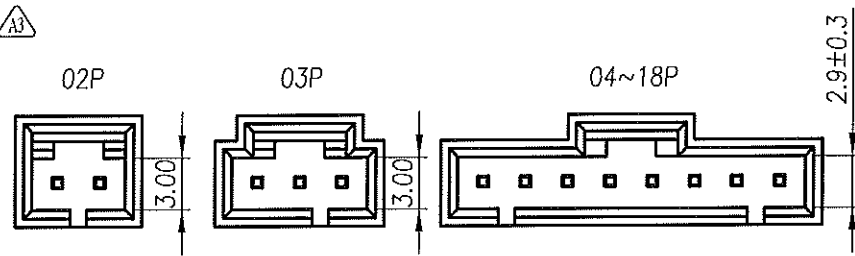
1.Housing:Black  
2.Contact Pin:See P/N Option

Part No.:AD03800 XX 8 3 5 A

No. Of Pin 02~18	Packing 5:Bag
Housing Material 8:PBT UL94V-0 Black	Plating 3:Gold Flash Over Nickel



Pin	DIM.A	DIM.B	DIM.C	Pin	DIM.A	DIM.B	DIM.C
02	2.54	5.72	7.62	11	25.40	28.58	30.48
03	5.08	8.26	10.16	12	27.94	31.12	33.02
04	7.62	10.80	12.70	13	30.48	33.66	35.56
05	10.16	13.34	15.24	14	33.02	36.20	38.10
06	12.70	15.88	17.78	15	35.56	38.74	40.64
07	15.24	18.42	20.32	16	38.10	41.28	43.18
08	17.78	20.96	22.86	17	40.64	43.82	45.72
09	20.32	23.50	25.40	18	43.18	46.36	48.26
10	22.86	26.04	27.94				



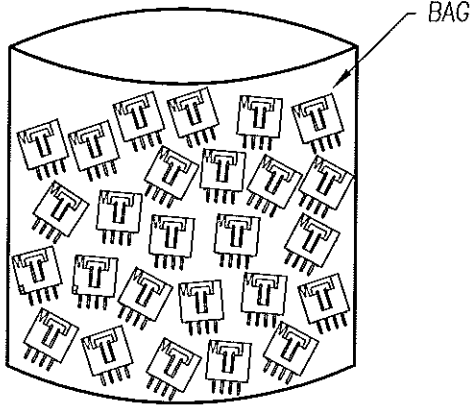
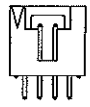
**金上達科技股份有限公司**  
GOLDENSUNDA TECHNOLOGY CO.,LTD

TOLERANCE UNLESS OTHERWISE SPECIFIED		PROJ.	TITLE: Wire To Board Wafer 2.54mm 180' DIP Single Row	
.x± 0.35	x'± 2'	APR. C.F.Liao 20160219	PART NO. AD03800XX835A	DWG NO. AD03800XX835A
.xx± 0.25	.x'± 1'	CHK. Abel 20160219	UNITS: mm	CUSTOMER DRAWING
.xxx± 0.15	.xx'± 0.5'	DRW. Michelle 20160219	SIZE: A4	SCALE 3:1
			SHEET 1 / 2	REV A3 V

RoHS Compliant

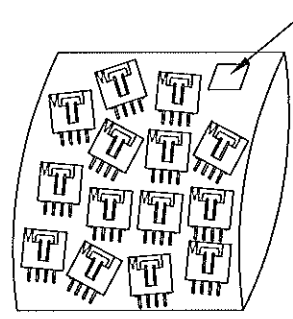


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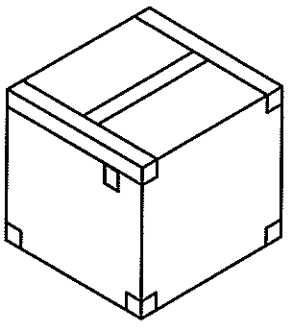
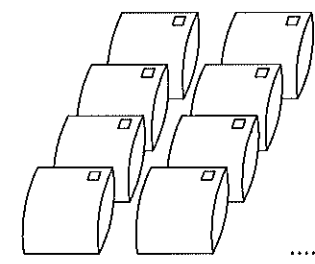
BAG

PIN	Q'TY
02~05	1000
06~12	500

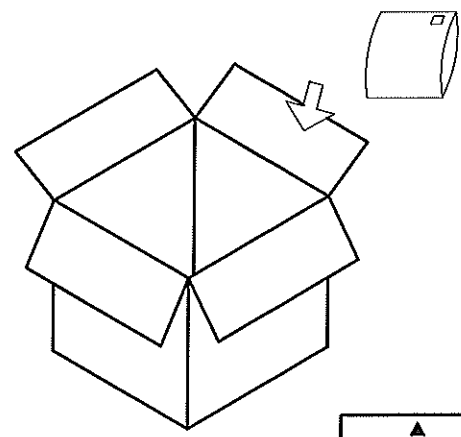


LABEL

SEAL THE BAG



CLOSE CARTON WITH TAPE.



INTO THE CARTON, QT'Y BY OTHER.



		<b>金上達科技股份有限公司</b> <b>GOLDENSUNDA TECHNOLOGY CO.,LTD</b>			
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.X± 0.35	X'± 2'	PROJ.	APR. C.F.Liao 20160219	PART NO. ADO3800XX835A	DWG NO. ADO3800XX835A
.XX± 0.25	.X'± 1'	CHK. Abel 20160219	UNITS: mm	CUSTOMER DRAWING	
.XXX± 0.15	.XX'± 0.5'	DRA. Michelle 20160219	SIZE: A4	SCALE Free	SHEET 2 / 2
			REV A3	V	